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April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)
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MOS FIELD EFFECT TRANSISTOR μ PA1807

N-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

DESCRIPTION

The μ PA1807 is a switching device, which can be driven directly by a 4.0 V power source.

This device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as DC/DC converters and power management of notebook computers and so on.

FEATURES

- 4.0 V drive available
- Low on-state resistance

 $R_{DS(on)1} = 10 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 10 \text{ V, Ip} = 6.0 \text{ A)}$

 $R_{DS(on)2} = 14 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 4.5 \text{ V, Ip} = 6.0 \text{ A)}$

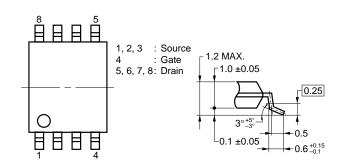
 $R_{DS(on)3} = 16 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 4.0 \text{ V, Ip} = 6.0 \text{ A)}$

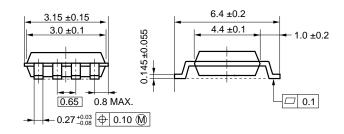
• Built-in G-S protection diode against ESD

ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1807GR-9JG	Power TSSOP8

PACKAGE DRAWING (Unit: mm)

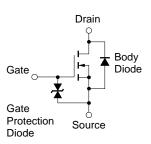




ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Drain to Source Voltage (Vgs = 0 V)	Voss	30	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (T _A = 25°C)	$\begin{array}{ll} \text{(DC) (TA = 25^{\circ}\text{C)}} & \text{ID(DC)} & \pm 12 \\ \text{(pulse)} & \text{ID(pulse)} & \pm 48 \end{array}$		Α
Drain Current (pulse) Note1	D(pulse)	±48	Α
Total Power Dissipation Note2	PT	2.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

EQUIVALENT CIRCUIT



Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Mounted on ceramic substrate of 5000 mm² x 1.1 mm

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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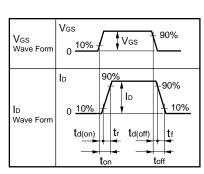


ELECTRICAL CHARACTERISTICS (TA = 25°C)

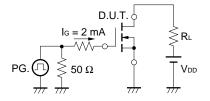
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Inss	V _{DS} = 30 V, V _{GS} = 0 V			1.0	μΑ
Gate Leakage Current	Igss	V _G S = ±20 V, V _D S = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1.0 mA	1.5	2.0	2.5	V
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 6.0 A	7.0	15		S
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, ID = 6.0 A		8.1	10	mΩ
	RDS(on)2	Vgs = 4.5 V, ID = 6.0 A		10.5	14	mΩ
	RDS(on)3	V _{GS} = 4.0 V, I _D = 6.0 A		12	16	mΩ
Input Capacitance	Ciss	Vps = 10 V		1000		pF
Output Capacitance	Coss	V _G S = 0 V		390		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		140		pF
Turn-on Delay Time	t d(on)	V _{DD} = 15 V, I _D = 6.0 A		16		ns
Rise Time	tr	V _G s = 10 V		11		ns
Turn-off Delay Time	td(off)	R _G = 10 Ω		46		ns
Fall Time	tf			11.5		ns
Total Gate Charge	Q _G	V _{DD} = 24 V		19		nC
Gate to Source Charge	Qgs	V _G s = 10 V		3.1		nC
Gate to Drain Charge	Q _{GD}	I _D = 12 A		5.0		nC
Body Diode Forward Voltage	V _{F(S-D)}	IF = 12 A, Vgs = 0 V		0.82		V
Reverse Recovery Time	trr	IF = 12 A, Vgs = 0 V		32		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		24		nC

TEST CIRCUIT 1 SWITCHING TIME

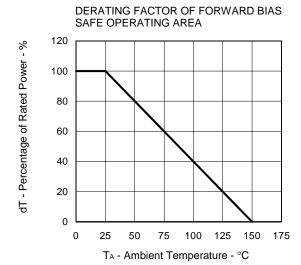
PG. \uparrow R_{Rg} \downarrow V_{DD} $\tau = 1 \, \mu \text{s}$ Duty Cycle $\leq 1\%$



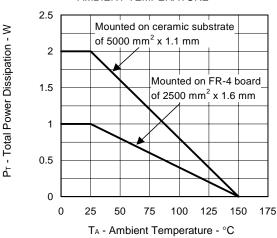
TEST CIRCUIT 2 GATE CHARGE



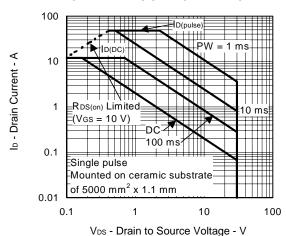
TYPICAL CHARACTERISTICS (TA = 25°C)

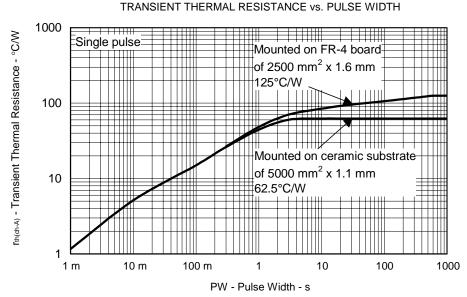


TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA



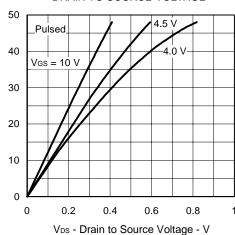


3

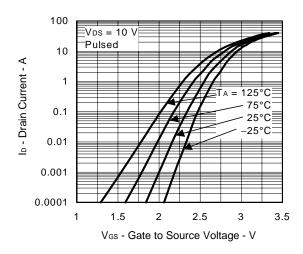
lo - Drain Current - A

Ves(off) - Gate Cut-off Voltage - V

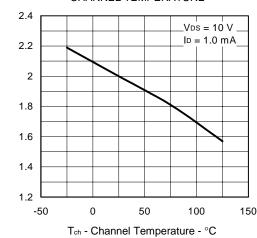
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



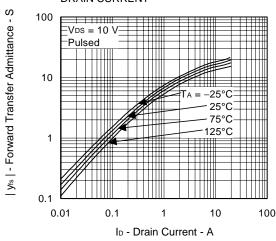
FORWARD TRANSFER CHARACTERISTICS



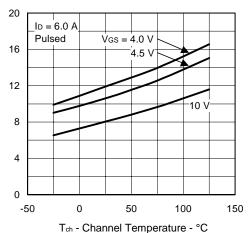
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



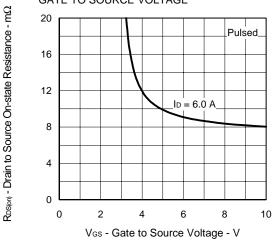
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



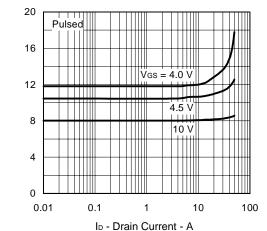
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



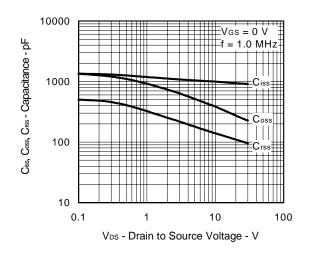
Ros(on) - Drain to Source On-state Resistance - mΩ

RDS(m) - Drain to Source On-state Resistance - m\Omega

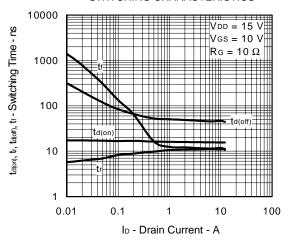
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



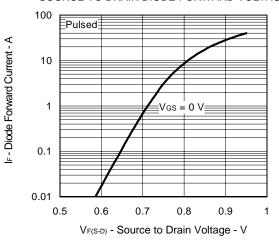
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



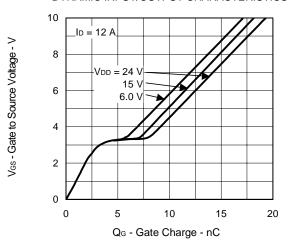
SWITCHING CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



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